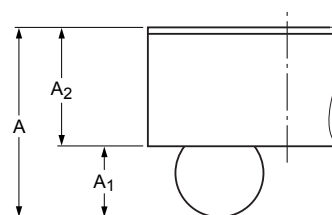
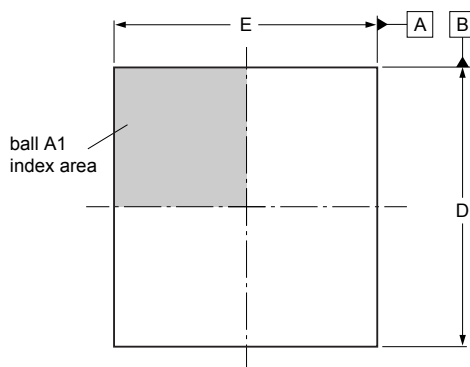
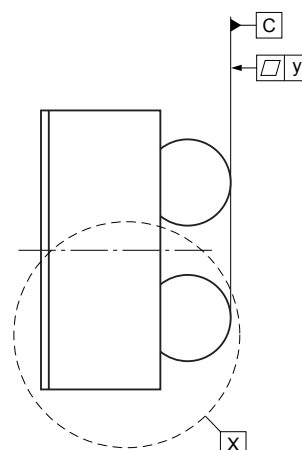
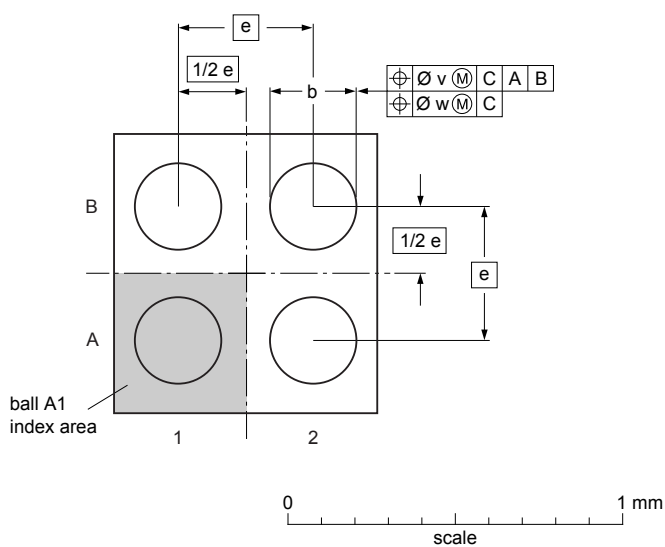


WLCSP4: wafer level chip-scale package; 4 bumps; 0.83 x 0.78 x 0.53 mm (backside coating included)

SOT1375-3



detail X



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	v	w	y
max	0.577	0.240	0.338	0.310	0.855	0.805				
mm nom	0.530	0.210	0.322	0.260	0.830	0.780	0.4	0.02	0.015	0.03
min	0.483	0.180	0.306	0.233	0.805	0.755				

wlcspp4_pca9618uk_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1375-3					14-02-05 15-10-01